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(54) **PRINTED CIRCUIT BOARD**

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(57) **ABSTRACT**

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A printed circuit board includes: a first insulating layer; a via pad disposed on an upper surface of the first insulating layer; a second insulating layer disposed on the upper surface of the first insulating layer and having a via hole exposing at least a portion of an upper surface of the via pad; a conductor pattern disposed on the exposed upper surface of the via pad; and a via including a first metal layer covering at least a portion of each of a wall surface of the via hole, the exposed upper surface of the via pad, and the conductor pattern, and a second metal layer disposed on the first metal layer and disposed in at least a portion of the via hole.

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